

ABSTRACT OF THE DISCLOSURE

A semiconductor chip is attached to a lead frame with a
filmy organic die-bonding material having a water absorption of
5 1.5% by volume or less; having a saturation moisture absorption
of 1.0% by volume or less, having a residual volatile component in
an amount not more than 3.0% by weight, having a modulus of
elasticity of 10 MPa or less at a temperature of 250 °C. The
semiconductor device thus obtained can be free from occurrence
10 of reflow cracks during reflow soldering for the packaging of
semiconductor devices.

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